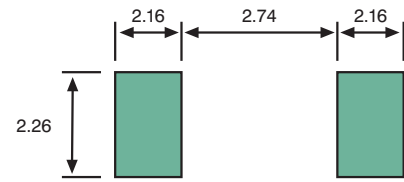


**FEATURES**

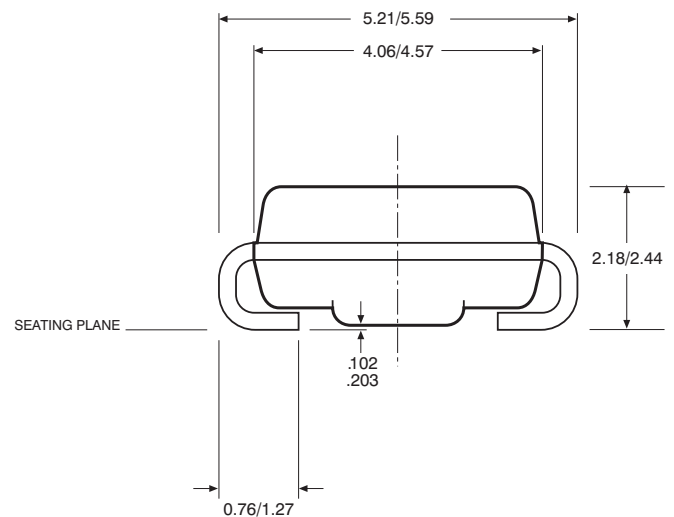
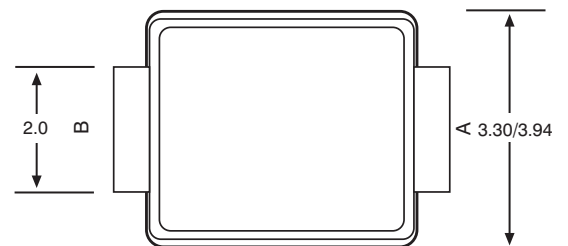
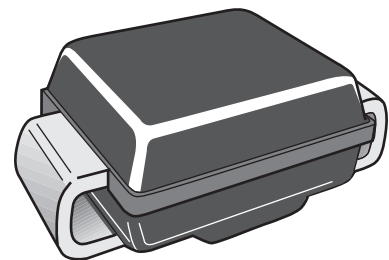
- Bi-directional transient voltage protection
- Glass passivated junction
- Nano second clamping response
- Surge capability up to 250 (Amps)
- No performance degradation under service life
- Industry standard DO-2144AA Jedec outline
- Available on tape (12mm)
- UL recognised

**MECHANICAL CHARACTERISTICS**

- Transfer molded, void free epoxy body
- Terminals: modified 'J' bend for large contact area
- Tin/Lead plated leads
- Maximum case temperature for soldering purposes: 230°C for 10 seconds
- Standard packaging: 12mm tape (meets EIA 481-1)
- Device marking, device code, logo



Solder Pads  
All dimensions in mm



**ELECTRICAL CHARACTERISTICS @ 25°C Tamb**

SYMBOL	PARAMETER		
V <sub>RM</sub>	Stand-off voltage	I <sub>RM</sub>	Stand-off current
V <sub>BR</sub>	Breakdown voltage	I <sub>BO</sub>	Breakover current
V <sub>BO</sub>	Breakover voltage	I <sub>H</sub>	Holding current
V <sub>T</sub>	On-state voltage		

**ABSOLUTE RATINGS**

SYMBOL	PARAMETER	VALUE			
		Type A	Type B		
I <sub>pp</sub>	Peak Pulse Current	10/1000 μsec	50	100	A
		8-20 μs expo	150	250	A
I <sub>tsm</sub>	Non-repetitive surge peak on-state current	tp20 ms	30		A
di/dt	Critical rate of rise of on-state current	Non-repetitive	100		A/μs
T <sub>stg</sub>	Storage and operating junction temperature range		-40 to +150		°C
T <sub>j</sub>			150		°C
TL	Maximum temperature for soldering (For period of 10 seconds max)		230		°C

Device Type	V <sub>rm</sub>	I <sub>rm</sub> @ V <sub>rm</sub> (μA)	V <sub>br</sub> MIN	V <sub>bo</sub> MAX	V <sub>t</sub> TYP @ 1A	I <sub>bo</sub> TYP (mA)	I <sub>h</sub> MIN (mA)
SMTBJ050 A or B	50	1	60	80	<2V	50	150
SMTBJ070 A or B	70	1	80	120	<2V	50	150
SMTBJ100 A or B	100	1	110	135	<2V	50	150
SMTBJ120 A or B	120	1	140	165	<2V	50	150
SMTBJ170 A or B	170	1	180	215	<2V	50	150
SMTBJ200 A or B	200	1	220	265	<2V	50	150

All parameters are tested using Fet Test™ Model 3600.